

Data sheet acquired from Harris Semiconductor SCHS056

CMOS OR Gates

High-Voltage Types (20-Volt Rating)

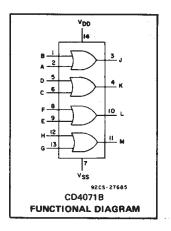
CD4071B Quad 2-Input OR Gate CD4072B Dual 4-Input OR Gate CD4075B Triple 3-Input OR Gate

CD4071B, CD4072B, and CD4075B OR gates provide the system designer with direct implementation of the positive-logic OR function and supplement the existing family of CMOS gates. The CD4071, CD4072, and CD4075 types are supplied in 14-lead dual-in-line ceramic packages (D and F suffixes), 14-lead dual-in-line plastic packages (E suffix), and in chip form (H suffix).

CD4071B, CD4072B, CD4075B Types

Features:

- Medium-Speed Operation-tpLH, tpHL = 60 ns (typ.) at V_{DD} = 10 V
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25 °C
- Standardized, symmetrical output characteristics
- Noise margin (over full package temperature range)
 - 1 V at V_{DD} = 5 V 2 V at V_{DD} = 10 V
- 2.5 V at V_{DD} = 15 V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



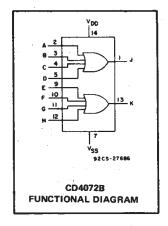
RECOMMENDED OPERATING CONDITIONS

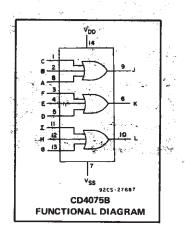
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIN	UNITS	
	MIN.	MAX.	
Supply-Voltage Range (For TA = Full Package-Temperature Range)	3	18	٧

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER-	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							
ISTIC	Vo	VIN	V _{DD} (V)					+25			UNITS
	(V)	(V)		-55	-40	+85	+125	Min.	Тур.	Max.]
Quiescent Device		0,5	5	0.25	0.25	7.5	7.5	_	0.01	0.25	μΑ
Current,	-	0,10	10	0.5	0.5	15	15	-	0.01	0.5	
IDD Max.	-	0,15	15	1	1	30	30	-	0.01	1	
		0,20	20	5	5	150	150	-	0.02	5	
Output Low	0.4	0,5	5	0.64	0.61	0.42	0,36	0.51	1	-	
(Sink) Current	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	_	
Output High	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	_	mA
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	
Current, IOH Min.	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
TOH WIIII.	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	6.8	-	
Output Voltage:	-	0,5	5	0.05				0	0.05		
Low-Level, VOI Max.	_	0,10	10	0.05				-	0	0.05	
VOL WAX.	_	0,15	15	0.05					0	0.05	
Output Voltage:		0,5	5	4.95			4.95	5	_	•	
High-Level,	_	0,10	10	9.95				9.95	10	-	
VOH Min.		0,15	15	14.95				14.95	15	-	
Input Low	0.5, 4.5		. 5	1.5				_	Γ-	1.5	
Voltage,	1, 9	_	10	3				-	_	3	- v
VIL Max.	1.5,13.5	÷	15	4				_	_	4	
Input High	4.5	_	5	3.5				3.5			
Voltage,	9	, ,	10	7				7			
VIH Min.	13.5	_	15	11				11	<u> </u>	_	
Input Current I _{IN} Max.	ž.	0,18	18	±0.1	±0.1	±1	±1	<u>-</u> .	±10 ⁻⁵	±0.1	μА





CD4071B, CD4072B, CD4075B Types

MAXIMUM RATINGS, Absolute-Maximum Values:	
DC SUPPLY-VOLTAGE RANGE, (VDD)	'
Voltages referenced to VSS Terminal)0.5\	/ to +20V
INPUT VOLTAGE RANGE, ALL INPUTS0.5V to V	+0.5V
DC INPUT CURRENT, ANY ONE INPUT	
POWER DISSIPATION PER PACKAGE (PD):	
For T _A = -55°C to +100°C	500mW
For T _A = +100°C to +125°C	200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	100mW
OPERATING-TEMPERATURE RANGE (TA)55°C to	+125°C
STORAGE TEMPERATURE RANGE (Tstg)65°C to	+150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 \pm 1/32 inch (1.59 \pm 0.79mm) from case for 10s max	+265°C

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C, Input t_r, t_f = 20 ns, and C_L = 50 pF, R_L = 200 $~k\Omega$

CHARACTERISTIC	TEST COND	TIONS	ALL.	UNITS	
		V _{DD} VOLTS	TYP.	MAX.	
Propagation Delay Time, ^t PHL, ^t PLH		5 10 15	125 60 45	250 120 90	ns
Transition Time, ^t THL ^{, t} TLH		5 10 15	100 50 40	200 100 80	ns
Input Capacitance, C _{IN}	Any Input	1 – 1	5	7.5	pF

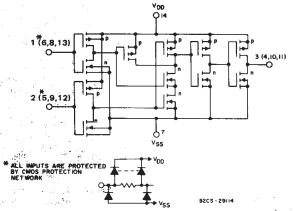


Fig. 3 - Schematic diagram for CD4071B (1 of 4 identical gates).

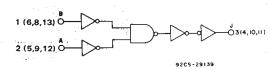


Fig. 5 -/ Logic diagram for CD4071B (1 of 4 identical gates).

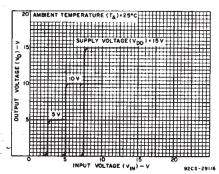


Fig. 1 — Typical voltage transfer characteristics

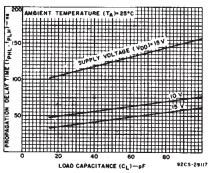


Fig. 2 — Typical propagation delay time as a function of load capacitance.

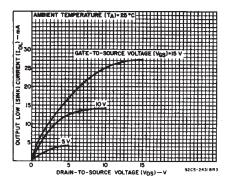


Fig. 4 — Typical output low (sink) current characteristics.

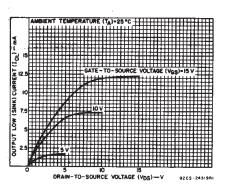
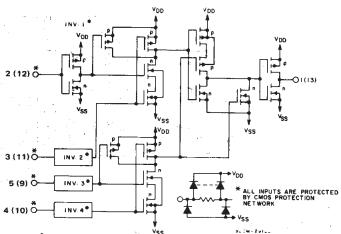


Fig. 6 — Minimum output low (sink) current characteristics.

CD4071B, CD4072B, CD4075B Types



INVERTERS 2,3 AND 4 ARE IDENTICAL TO INVERTER 1.

Fig. 7 - Schematic diagram for CD4072B (1 of 2 identical gates).

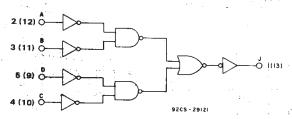


Fig. 9 - Logic diagram for CD4072B (1 of 2 identical gates).

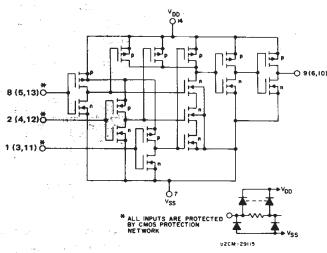


Fig. 11 - Schematic diagram for CD4075B (1 of 3 identical gates).

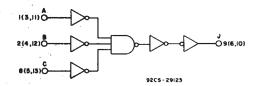


Fig. 13 - Logic diagram for CD4075B (1 of 3 identical gates).

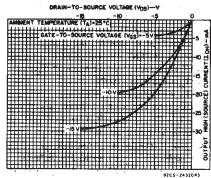


Fig. 8 — Typical output high (source) current characteristics.

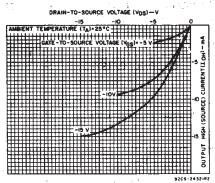


Fig. 10 – Minimum output high (source) current characteristics.

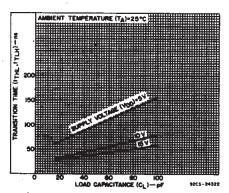


Fig. 12 — Typical transition time as a function of load capacitance.

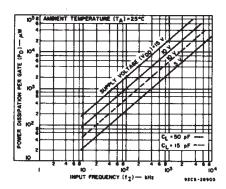
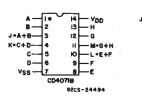
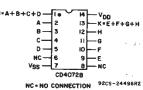


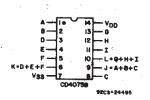
Fig. 14 – Typical dyanamic power dissipation as a function of frequency.

CD4071B, CD4072B, CD4075B Types

TERMINAL ASSIGNMENTS (TOP VIEW)







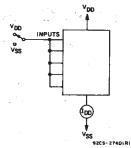


Fig. 15 - Quiescent device current test circuit.

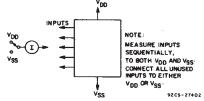


Fig. 16 - Input current test circuit.

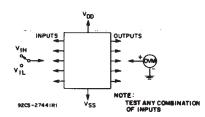
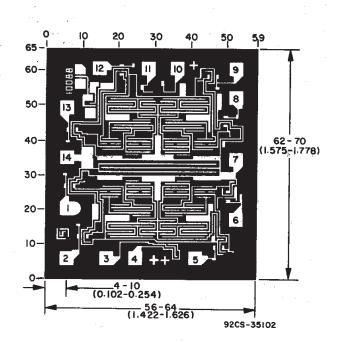
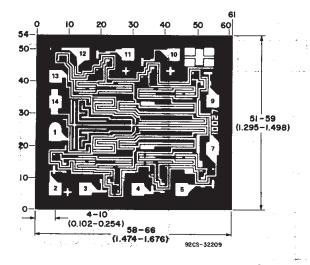


Fig. 17 - Input-voltage test circuit.

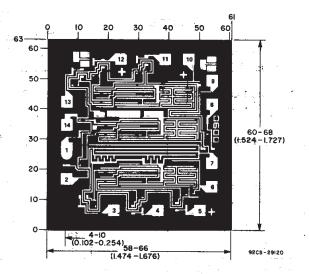
Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch).



Chip dimensions and pad layout for CD4071B.



Chip dimensions and pad layout for CD4072B.



Chip dimensions and pad layout for CD4075B.

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